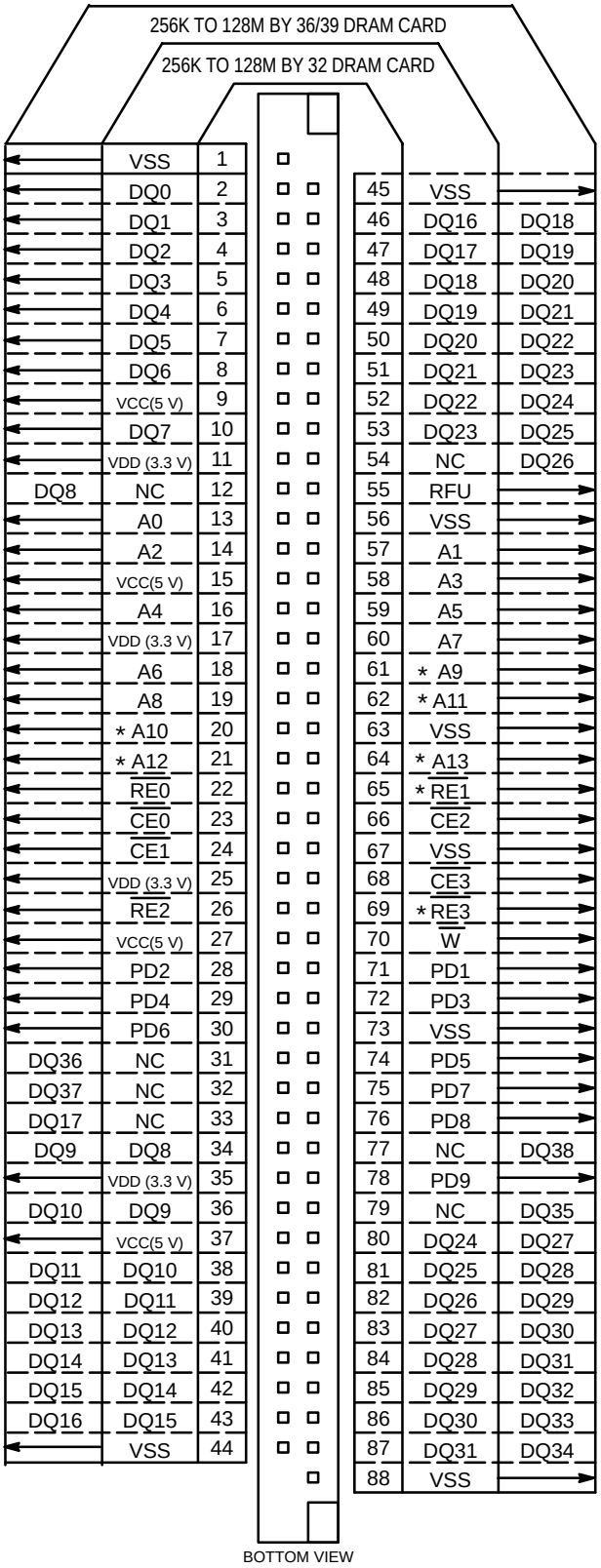
4.4.3 – 88 PIN DRAM CARD FAMILIES

NOTE: There are two versions of this Card, shown in Figure 4.4.3–1 describing X 32 & 36/39 configurations, & 4.4.3–2 describing a X 40 configuration. They are similar but not fully compatible. Caution should be exercised in using these standards.

CAPACITY—256K TO 128M WORDS OF 32, 36, 39 OR 40 BITS
CONFIGURATION—16 Different Configurations Using 1mb, 4mb, 16mb, 64mb, & 256mb Devices And With 2, Or 4 $\overline{Re}$ Clocks.
LOGIC FEATURES—The cards may be used with DATA BUS widths of X16/18 or X32/36 or X39— The cards contain a "PRESENCE DETECT" feature which conists of output pins which supply an encoded value which defines the storage capacity, configuration, and speed of the card.
PIN ASSIGNMENTS, 32, 36, & 39 bit—Fig. 4.4.3–1 A
PRESENCE DETECT TABLE 32, 36, & 39 bit—Fig. 4.4.3–1 B
CONFIGURATION BLOCK DIAGRAMS 32, 36, & 39 bit—Figs. 4.4.3–1 C, 4.4.3–1 D, 4.4.3–1 E, & 4.4.3–1 F
PIN ASSIGNMENTS, 40 bit—Fig. 4.4.3–2 A
PRESENCE DETECT TABLE 40 bit—Fig. 4.4.3–2 B
CONFIGURATION BLOCK DIAGRAMS 40 bit—Figs. 4.4.3–2 C, 4.4.3–2 D, 4.4.3–2 E, & 4.4.3–2 F
PACKAGE—88 PIN JEDEC MEMORY CARD



	PD7	PD6
SPEED (tRAC)	75	30
100 nS	VSS	VSS
80 nS	VSS	NC
70 nS	NC	VSS
60 nS	NC	NC
50 nS	VSS	VSS

PD SPEED TABLE

	PIN NUMBER						
CONFIGURATION	20	21	61	62	64	65	69
256K X 36, 2 $\overline{RE}$	NC	NC	NC	NC	NC	NC	NC
512K X 36, 4 $\overline{RE}$	NC	NC	NC	NC	NC	RE1	RE3
1M X 36, 2 $\overline{RE}$	NC	NC	A9	NC	NC	NC	NC
2M X 36, 4 $\overline{RE}$	NC	NC	A9	NC	NC	RE1	RE3
4M X 36, 2 $\overline{RE}$	A10	NC	A9	A11	NC	NC	NC
8M X 36, 4 $\overline{RE}$	A10	NC	A9	A11	NC	RE1	RE3
16M X 36, 2 $\overline{RE}$	A10	A12	A9	A11	NC	NC	NC
32M X 36, 4 $\overline{RE}$	A10	A12	A9	A11	NC	RE1	RE3
64M X 36, 2 $\overline{RE}$	A10	A12	A9	A11	A13	NC	NC
128M X 36, 4 $\overline{RE}$	A10	A12	A9	A11	A13	RE1	RE3

ADDRESS AND CLOCK PIN ASSIGNMENTS

Data Access Mode	PD9
FAST PAGE	NC
EDO	VSS

* SEE TABLE FOR FUNCTION ASSIGNMENTS FOR THESE PINS AS A FUNCTION OF CARD CAPACITY AND CONFIGURATION

FIGURE 4.4.3–1 A
88 PIN, BY 32 and 36/39 DRAM CARD PINOUT

PD BITS 5 4 3 2 1	CARD DENSITY	DRAM ORGANIZATION	CARD ADDR. REQ'D	RE ADDR.	CE ADDR.	AVAIL. PAGE DEPTH	AVERAGE REFRESH INTERVAL	NOTES
1 1 1 1 1	NO CARD							NO CARD INSTALLED
1 0 0 0 0	1 MB	256K X 1, 4, 16, 18	18	9	9	512	125 ms	
0 0 0 0 0	2 MB	256K X 1, 4, 16, 18	18	9	9	512	125 ms	
1 0 0 0 1	2 MB	512K X 8, 9	19	10	9	512	125 ms	
0 0 0 0 1	4 MB	512K X 8, 9	19	10	9	512	125 ms	
1 0 0 1 0	4 MB	1M X 1, 4, 16, 18	20	10	10	1024	125 ms	
0 0 0 1 0	8 MB	1M X 1, 4, 16, 18	20	10	10	1024	125 ms	
1 1 0 1 0	4 MB	1M X 16, 18	20	12	8	256	62 ms	
0 1 0 1 0	8 MB	1M X 16, 18	20	12	8	256	62 ms	
1 0 0 1 1	8 MB	2M X 8, 9	21	11	10	1024	125 ms	
0 0 0 1 1	16 MB	2M X 8, 9	21	11	10	1024	125 ms	
1 0 1 0 0	16 MB	4M X 1, 4, 16, 18	22	12	*11	**1024	62 ms	SUPPORT 12/10 AND 11/11 ADDRESS
0 0 1 0 0	32 MB	4M X 1, 4, 16, 18	22	12	*11	**1024	62 ms	SUPPORT 12/10 AND 11/11 ADDRESS
1 0 1 0 1	32 MB	8M X 8, 9	23	13	*11	**1024	62 ms	SUPPORT 13/10 AND 12/11 ADDRESS
0 0 1 0 1	64 MB	8M X 8, 9	23	13	*11	**1024	62 ms	SUPPORT 13/10 AND 12/11 ADDRESS
1 0 1 1 0	64 MB	16M X 1, 4, 16, 18	24	14	*11	**1024	31 ms	SUPPORT 13/11 AND 14/10 ADDRESS
0 0 1 1 0	128MB	16M X 1, 4, 16, 18	24	14	*11	**1024	31 ms	SUPPORT 13'/11 AND 14/10 ADDRESS

* INDICATES REDUNDANT ADDRESS THAT MUST BE PROVIDED AT CE\ TIME (TO ALLOW USE OF MIXED DRAM ADDRESSING)
** PAGE DEPTH DETERMINED BY THE SMALLEST CE\ ADDRESS DRAM
*** ALL DENSITIES ASSUME 4 BYTE CARD DATA WIDTH (32 OR 36 BITS)
FOR THE PDn PINS, 1 = NC, 0 = VSS

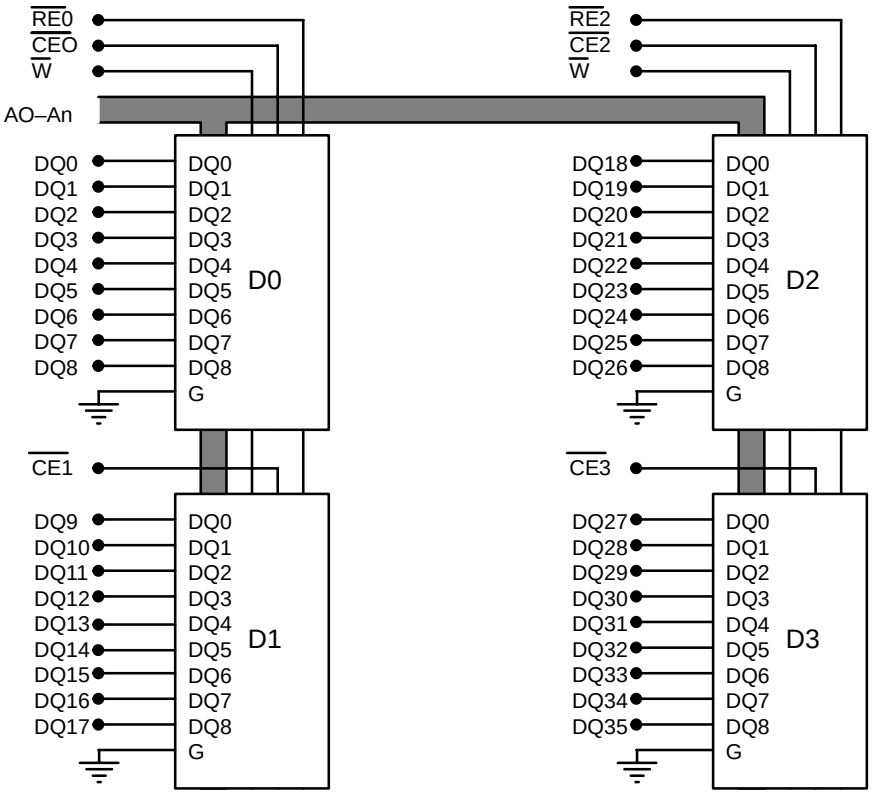
MEMORY CARD ORGANIZATION AND ADDRESS STRUCTURE

BASE DEVICE	CONFIG'N	PIN NUMBER 9	11	15	17	25	27	35	37
1M	256K X 36, 2 $\overline{RE}$	5 V	NC	5 V	NC	NC	5 V	NC	5 V
1M	512K X 36, 4 $\overline{RE}$	5 V	NC	5 V	NC	NC	5 V	NC	5 V
4M	1M X 36, 2 $\overline{RE}$	5 V,NC	NC, 3.3 V	5 V, NC	NC, 3.3 V	NC, 3.3 V	5 V, NC	NC, 3.3 V	5 V, NC
4M	2M X 36, 4 $\overline{RE}$	5 V, NC	NC, 3.3 V	5 V, NC	NC, 3.3 V	NC, 3.3 V	5 V, NC	NC, 3.3 V	5 V, NC
16M	4M X 36, 2 $\overline{RE}$	5 V, NC	NC, 3.3 V	5 V, NC	NC, 3.3 V	NC, 3.3 V	5 V, NC	NC, 3.3 V	5 V, NC
16M	8M X 36, 4 $\overline{RE}$	5 V, NC	NC, 3.3 V	5 V, NC	NC, 3.3 V	NC, 3.3 V	5 V, NC	NC, 3.3 V	5 V, NC
64M	16M X 36, 2 $\overline{RE}$	NC	3.3 V	NC	3.3 V	3.3 V	NC	3.3 V	NC
64M	32M X 36, 4 $\overline{RE}$	NC	3.3 V	NC	3.3 V	3.3 V	NC	3.3 V	NC
256M	64M X 36, 2 $\overline{RE}$	NC	3.3 V	NC	3.3 V	3.3 V	NC	3.3 V	NC
256M	128M X 36, 4 $\overline{RE}$	NC	3.3 V	NC	3.3 V	3.3 V	NC	3.3 V	NC

VDD POWER PIN ASSIGNMENT TABLE

FIGURE 4.4.3–1 B
88 PIN, BY 32 AND 36/39 DRAM CARD CONFIGURATION TABLES

BLOCK DIAGRAM for 512K /2M/8M/32M X 36 or 1M/4M/16M/64M X 18 USING X8 or X9 DRAM



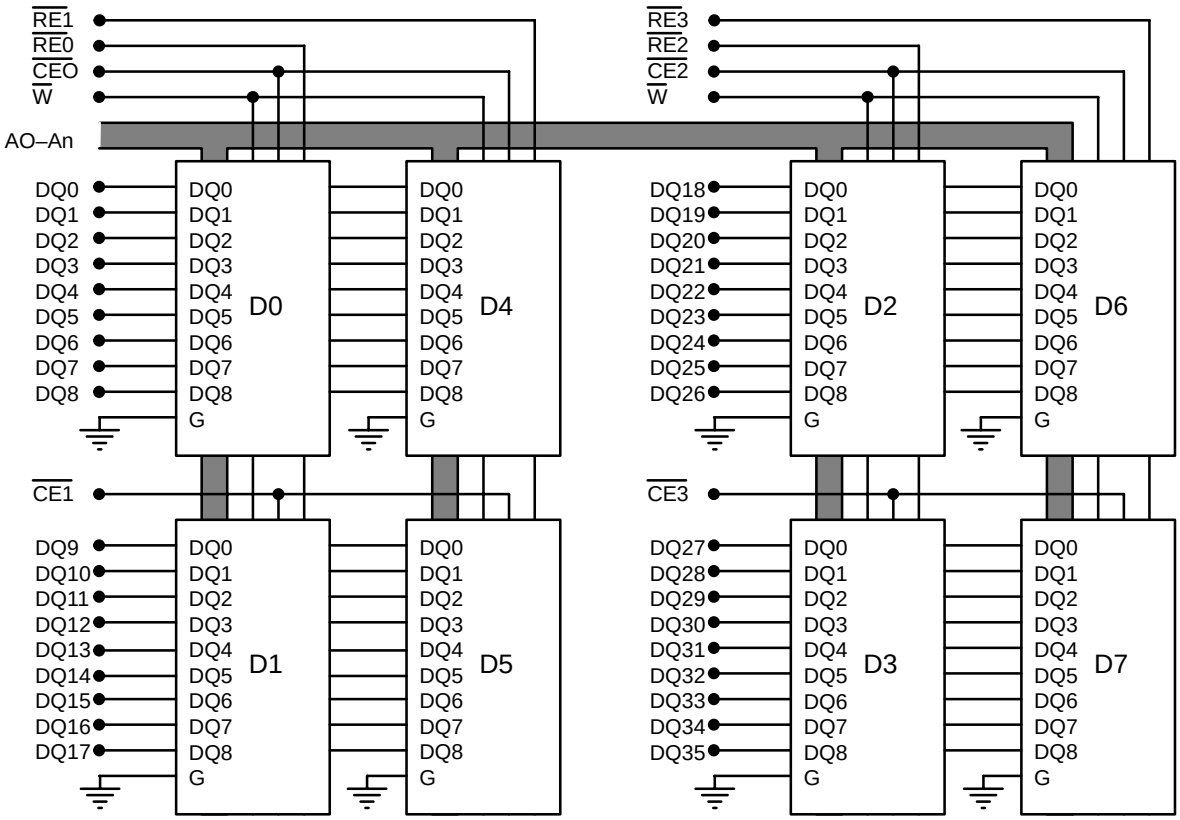
WORD ORGANIZATION	* BASE MEMORY DEVICE	
	D0 – D3	ADDRESS
512K X 36 or 1M X 18	4M (X9)	A0 – A9
2M X 36 or 4M X 18	16M (X9)	A0 – A10
8M X 36 or 16M X 18	64M (X9)	A0 – A12

* NOTE: The BASE MEMORY DEVICE columns give the total device capacity in bits and the data interface configuration

note 1: In an 18 bus system, $\overline{RE0}$ and $\overline{RE2}$ will be controlled independently and the data bus will be connected to for an 18 bit bus ourside the card
In a 36 bit system, $\overline{RE0}$ and $\overline{RE2}$ will be actuated simultaneously
note 2: The card contains 4 bytes of data; 2 byte operation is allowed.

FIGURE 4.4.3–1 C
88 PIN, BY 36, DRAM CARD 1 BANK USING BY 9 DEVICES

BLOCK DIAGRAM for 1M /4M/16M/64M X 36 or 2M/8M/32M/128M X 18
USING X8 or X9 DRAM



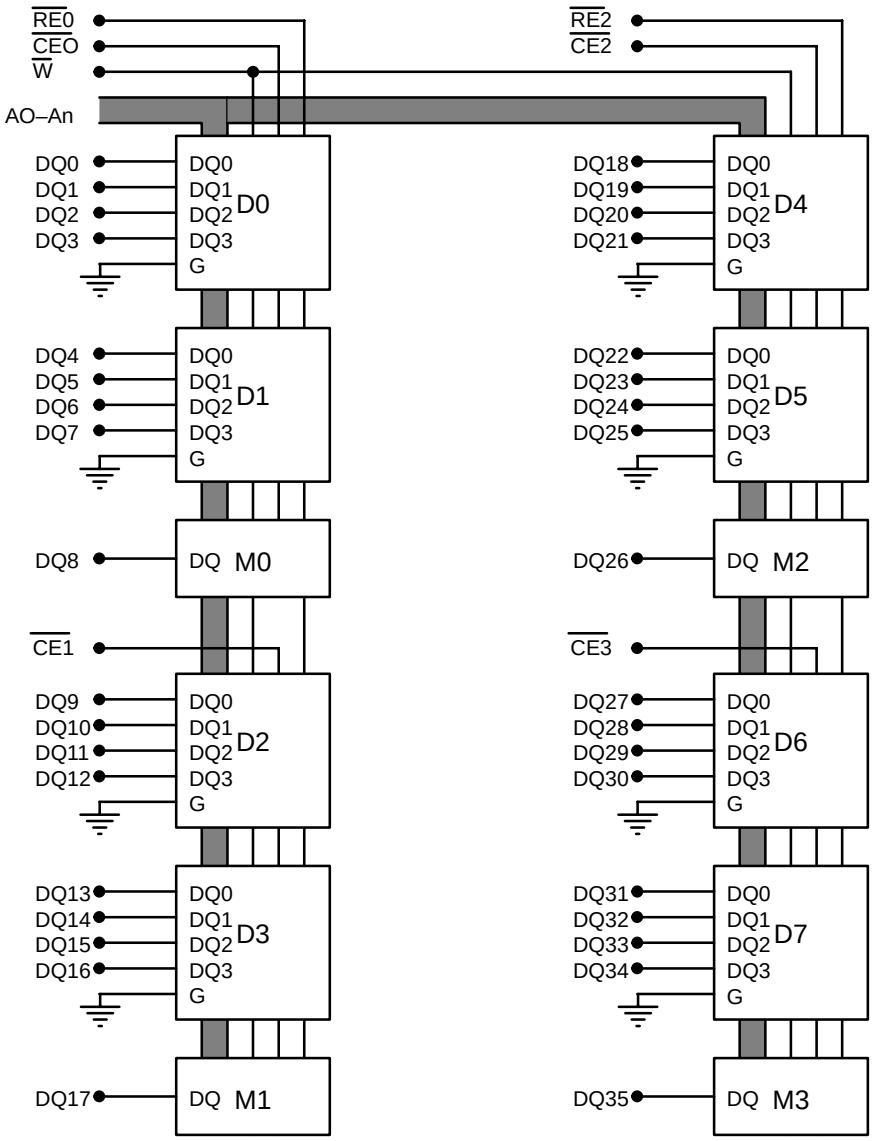
WORD ORGANIZATION	* BASE MEMORY DEVICE	
	D0 – D7	ADDRESS
1M X 36 or 2M X 18	4M (X9)	A0 – A9
4M X 36 or 8M X 18	16M (X9)	A0 – A10
16M X 36 or 32M X 18	64M (X9)	A0 – A12

* NOTE: The BASE MEMORY DEVICE columns give the total device capacity in bits and the data interface configuration

note 1: In an 18 bus system, $\overline{RE0}$ and $\overline{RE2}$ (also $\overline{RE1}$ and $\overline{RE3}$) will be controlled independently and the data bus will be connected to for an 18 bit bus ourside the card
In a 36 bit system, $\overline{RE0}$ and $\overline{RE2}$ (also $\overline{RE1}$ and $\overline{RE3}$) will be actuated simultaneously
note 2: The card contains 4 bytes of data; 2 byte operation is allowed.

FIGURE 4.4.3–1 D
88 PIN, BY 36, DRAM CARD 2 BANK USING BY 9 DEVICES

BLOCK DIAGRAM for 256K /1M/4M/16M/64M X 36 or 512K/2M/8M/32M/128M X 18 USING X4 and X1 DRAM



WORD ORGANIZATION	* BASE MEMORY DEVICE		
	D0 – D7	M0 – M3	ADDRESS
256K X 36 or 512K X 18	1M (X4)	256K (X1)	A0 – A8
1M X 36 or 2M X 18	4M (X4)	1M (X1)	A0 – A9
4M X 36 or 8M X 18	16M (X4)	4M (X1)	A0 – A11
16M X 36 or 32M X 18	64M (X4)	16M (X1)	A0 – A13

* NOTE: The BASE MEMORY DEVICE columns give the total device capacity in bits and the data interface configuration

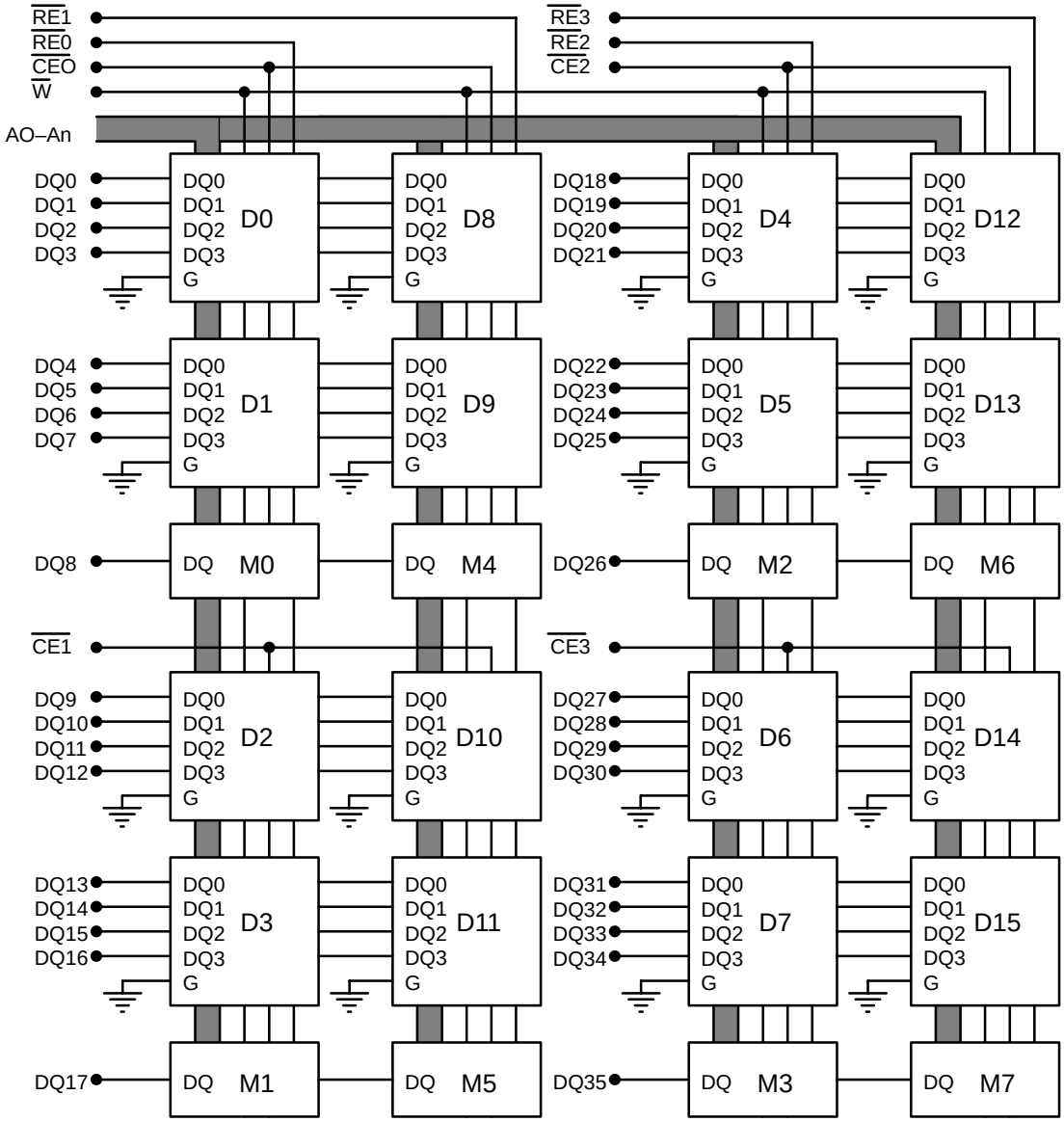
note 1: In an 18 bus system, $\overline{RE0}$ and $\overline{RE2}$ will be controlled independently and the data bus will be connected to for an 18 bit bus ourside the card
In a 36 bit system, $\overline{RE0}$ and $\overline{RE2}$ will be actuated simultaneously

note 2: The card contains 4 bytes of data; 2 byte operation is allowed.

FIGURE 4.4.3–1 E

88 PIN, 36, DRAM CARD 1 BANK USING BY 4 & BY 1 DEVICES

BLOCK DIAGRAM for 512K/2M/8M/32M/32M/128M X 36 or 1M/4M/16M/256M X 18 USING X4 and X1 DRAM



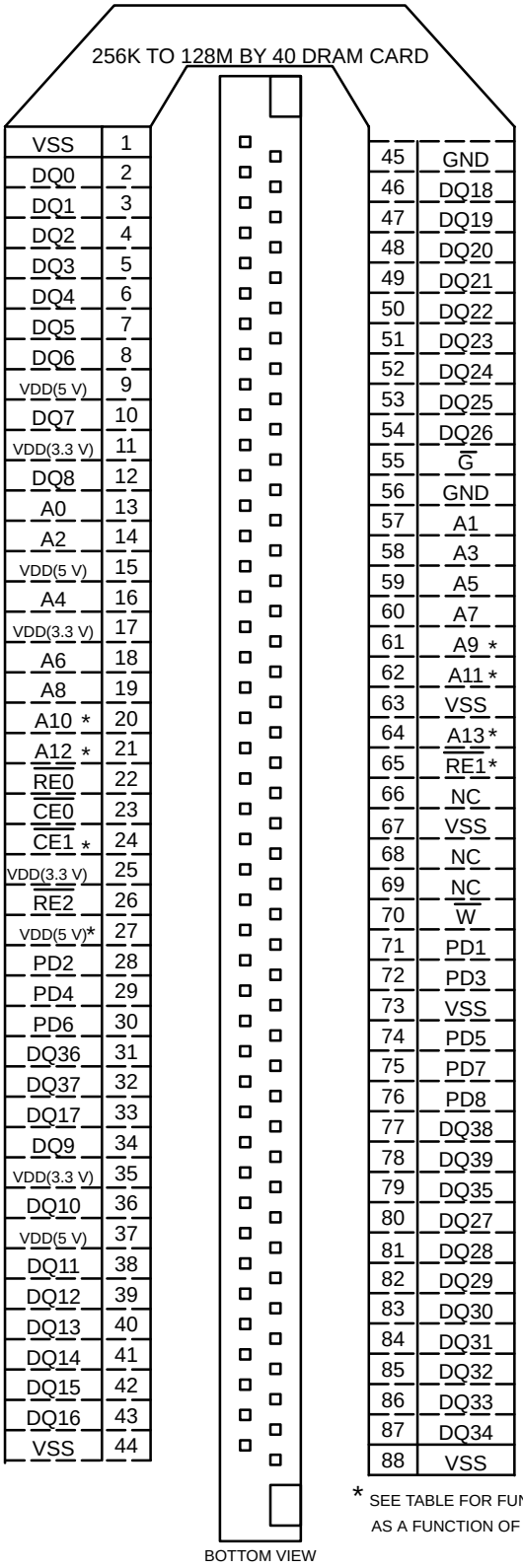
WORD ORGANIZATION	* BASE MEMORY DEVICE		
	D0 – D15	M0 – M7	ADDRESS
512K X 36 or 1M X 18	1M (X4)	256K(X1)	A0 – A8
2M X 36 or 4M X 18	4M (X4)	1M (X1)	A0 – A9
8M X 36 or 16M X 18	16M (X4)	4M (X1)	A0 – A11
32M X 36 or 64M X 18	64M (X4)	16M (X1)	A0 – A13

* NOTE: The BASE MEMORY DEVICE columns give the total device capacity in bits and the data interface configuration

note 1: In an 18 bus system, $\overline{RE0}$ and $\overline{RE2}$ (also $\overline{RE1}$ AND $\overline{RE3}$) will be controlled independently and the data bus will be connected to for an 18 bit bus ourside the card,
In a 36 bit system, $\overline{RE0}$ and $\overline{RE2}$ (also $\overline{RE1}$ and $\overline{RE3}$) will be actuated simultaneously
note 2: The card contains 4 bytes of data; 2 byte operation is allowed.

FIGURE 4.4.3–1 F

88 PIN, BY 36 DRAM CARD 2 BANK USING BY 4 & BY 1 DEVICES



* SEE TABLE FOR FUNCTIONAL ASSIGNMENTS FOR THESE PINS AS A FUNCTION OF CARD CAPACITY AND CONFIGURATION

Pin Assignment, Cards based on X4 DRAM

	Card Pin Number							
CONFIGURATION	20	21	24	27	61	62	64	65
256K X 40 (1M)	NC	NC	NC	5 V, NC	NC	NC	NC	NC
512K X 40 (1M)	NC	NC	$\overline{CE1}$	5 V, NC	NC	NC	NC	$\overline{RE1}$
1M X 40 (4M)	NC	NC	NC	5 V, NC	A9	NC	NC	NC
2M X 40 (4M)	NC	NC	$\overline{CE1}$	5 V, NC	A9	NC	NC	$\overline{RE1}$
4M X 40 (16M)	A10	NC	NC	5 V, NC	A9	A11	NC	NC
8M X 40 (16M)	A10	NC	$\overline{CE1}$	5 V, NC	A9	A11	NC	$\overline{RE1}$
16M X 40 (64M)	A10	A12	NC	NC	A9	A11	NC	NC
32M X 40 (64M)	A10	A12	$\overline{CE1}$	NC	A9	A11	NC	$\overline{RE1}$
64M X 40 (256M)	A10	A12	NC	NC	A9	A11	A13	NC
128M X 40 (256M)	A10	A12	$\overline{CE1}$	NC	A9	A11	A13	$\overline{RE1}$

Pin Assignment, Cards based on X8 DRAM

	Card Pin Number							
CONFIGURATION	20	21	24	27	61	62	64	65
512K X 40 (4M)	NC	NC	NC	5 V, NC	A9	NC	NC	NC
1M X 40 (4M)	NC	NC	$\overline{CE1}$	5 V, NC	A9	NC	NC	$\overline{RE1}$
2M X 40 (16M)	A10	NC	NC	5 V, NC	A9	A11	NC	NC
4M X 40 (16M)	A10	NC	$\overline{CE1}$	5 V, NC	A9	A11	NC	$\overline{RE1}$
8M X 40 (64M)	A10	A12	NC	NC	A9	A11	NC	NC
16M X 40 (64M)	A10	A12	$\overline{CE1}$	NC	A9	A11	NC	$\overline{RE1}$
32M X 40 (256M)	A10	A12	NC	NC	A9	A11	A13	NC
64M X 40 (256M)	A10	A12	$\overline{CE1}$	NC	A9	A11	A13	$\overline{RE1}$

ADDRESS AND CLOCK PIN ASSIGNMENTS

FIGURE 4.4.3–2 A
88 PIN, BY 40 DRAM CARD

	PD7	PD6
SPEED (tRAC)	P 75	P 30
80 nS	VSS	NC
70 nS	NC	VSS
60 nS	NC	NC
50 nS	VSS	VSS

PD SPEED TABLE

	PD8
REFRESH MODE	P 76
80 nS	VSS
70 nS	NC

PD REFRESH MODE TABLE

PD BITS 5 4 3 2 1	CARD DENSITY	DRAM ORGANIZATION	RE ADDR.	CE ADDR.	REFRESH PERIOD (mS) NORMAL	SLOW
1 1 1 1 1	NO CARD					
1 0 0 0 0	1 MB	256K X 4	9	9	8	64
0 0 0 0 0	2 MB	256K X 4	9	9	8	64
1 0 0 0 1	2 MB	512K X 8	10	9	16	128
0 0 0 0 1	4 MB	512K X 8	10	9	16	128
1 0 0 1 0	4 MB	1M X 4	10	10	16	128
0 0 0 1 0	8 MB	1M X 4	10	10	16	128
1 0 0 1 1	8 MB	2M X 8	11	10	32	256
0 0 0 1 1	16 MB	2M X 8	11	10	32	256
1 0 1 0 0	16 MB	4M X 4	11/12	11/10	64	256
0 0 1 0 0	32 MB	4M X 4	11/12	11/10	64	256
1 0 1 0 1	32 MB	8M X 8	12/13	11/10	TBD	TBD
0 0 1 0 1	64 MB	8M X 8	12/13	11/10	TBD	TBD
1 0 1 1 0	64 MB	16M X 4	13	11	TBD	TBD
0 0 1 1 0	128 MB	16M X 4	13	11	TBD	TBD
1 0 1 0 1	128 MB	32M X 8	TBD	TBD	TBD	TBD
0 0 1 0 1	256 MB	32M X 8	TBD	TBD	TBD	TBD
1 0 1 1 0	256 MB	64M X 4	TBD	TBD	TBD	TBD
0 0 1 1 0	512 MB	64M X 4	TBD	TBD	TBD	TBD

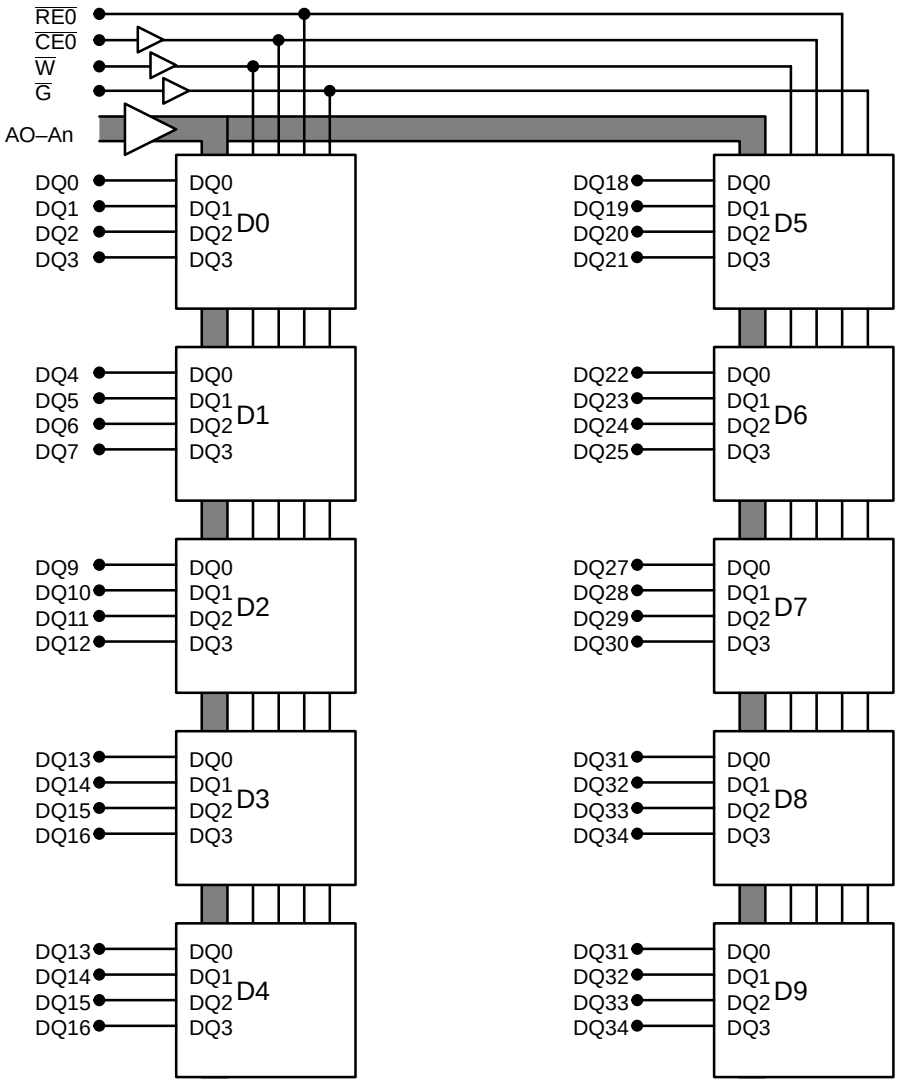
FOR THE PDn PINS, 1 = NC, 0 = VSS
NOTE: In the above address table, optional address configurations are given for some devices to allow for different approved refresh counts.

MEMORY CARD ORGANIZATION AND ADDRESS STRUCTURE

NOTE: The DRAM densities are shown in parentheses (xxxM)

FIGURE 4.4.3–2 B
88 PIN, BY 40 DRAM CARD PD TRUTH TABLE

BLOCK DIAGRAM for 256K/1M/4M/16M/64M X 40 USING X4 DRAM



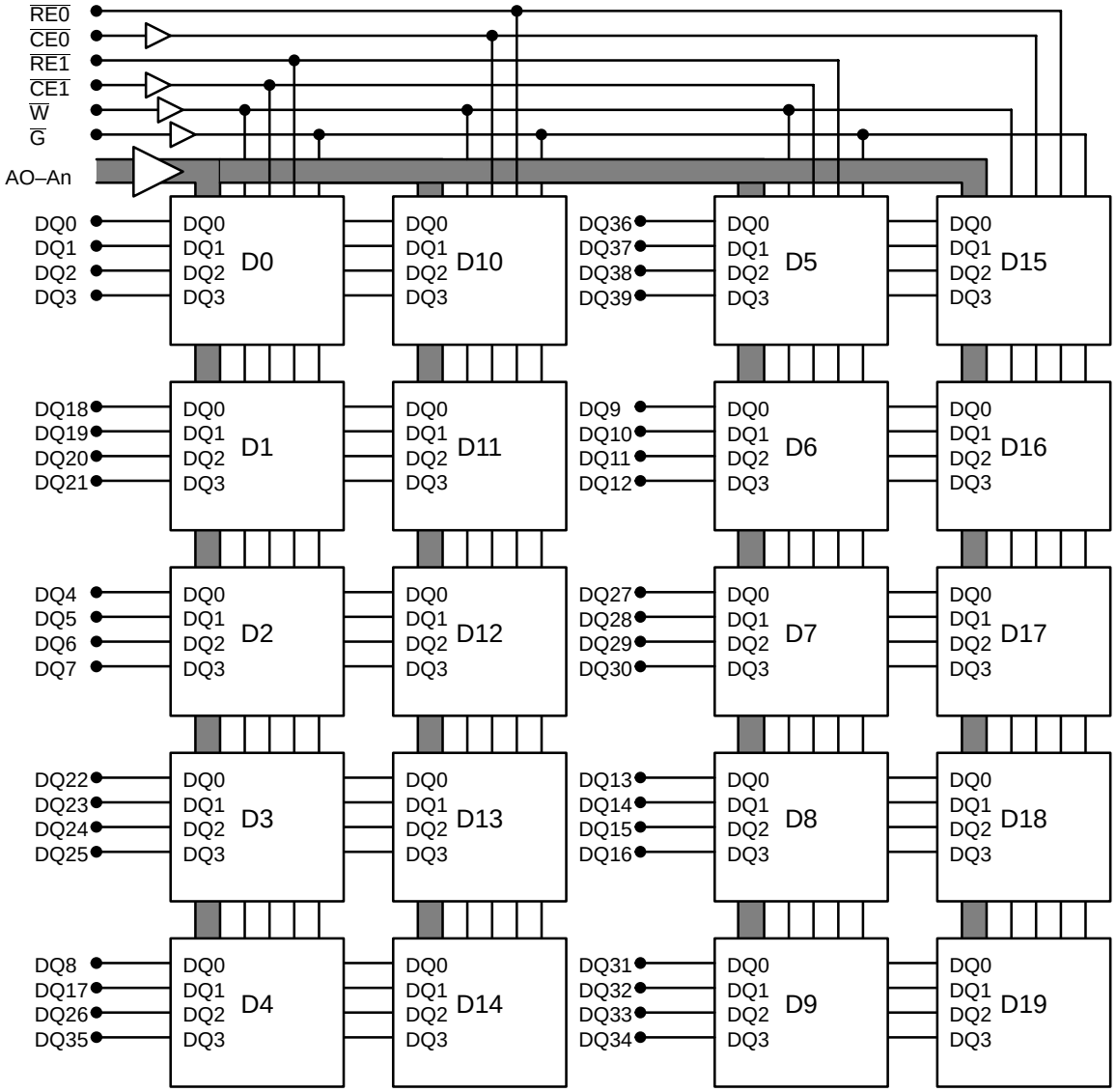
WORD ORGANIZATION	*Base Memory Device D0 to D9	ADDRESS FIELD	OPTIONAL ADDRESS
256K X 40	1M (X4)	A0 – A8	NA
1M X 40	4M (X8)	A0 – A9	NA
4M X 40	16M (X8)	A0 – A10	A0–A11
16M X 40	64M (X8)	A0 – A11	A0–A12
64M X 40	256M (X8)	TBD	TBD

* NOTE: The BASE MEMORY DEVICE columns give the total device capacity in bits and the data interface word width.

NOTE: There shall be one bypass capacitor between VDD and VSS fore each memory device on the card.

FIGURE 4.4.3–2 C
88 PIN, BY 40 DRAM CARD 1 BANK USING BY 4 DEVICES

BLOCK DIAGRAM for 1M/4M/16M/64M X 40 USING X8 DRAM



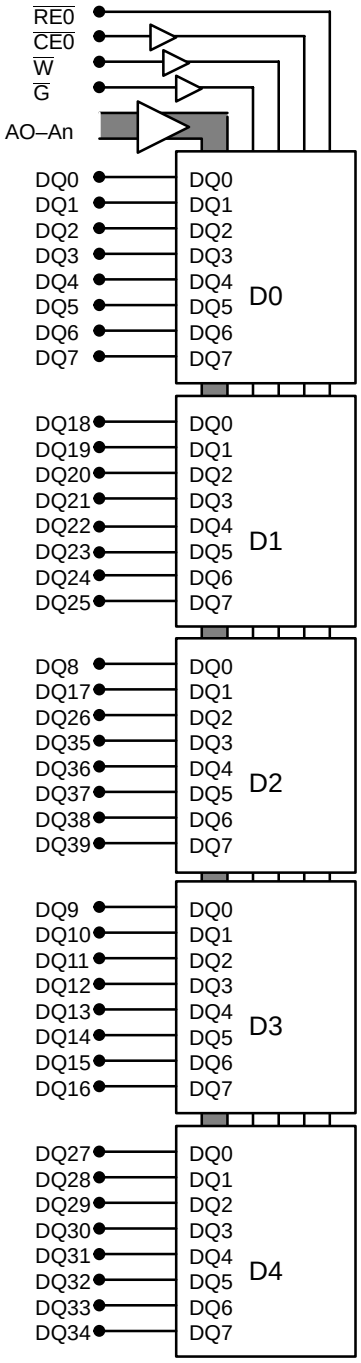
WORD ORGANIZATION	*Base Memory Device D0 to D19	ADDRESS FIELD	OPTIONAL ADDRESS
512K X 40	1M (X4)	A0 – A8	NA
2M X 40	4M (X8)	A0 – A9	NA
8M X 40	16M (X8)	A0 – A10	A0–A11
32M X 40	64M (X8)	A0 – A11	A0–A12
128M X 40	256M (X8)	TBD	TBD

* NOTE: The BASE MEMORY DEVICE columns give the total device capacity in bits and the data interface word width.

NOTE: There shall be one bypass capacitor between VDD and VSS fore each pair of memory devices on the card. The value of the capacitors will be determined by the memory devices used.

FIGURE 4.4.3–2 D
88 PIN, BY 40 DRAM CARD 2 BANK USING BY 4 DEVICES

BLOCK DIAGRAM for 512K/2M/8M/32M X 40 USING X8 DRAM



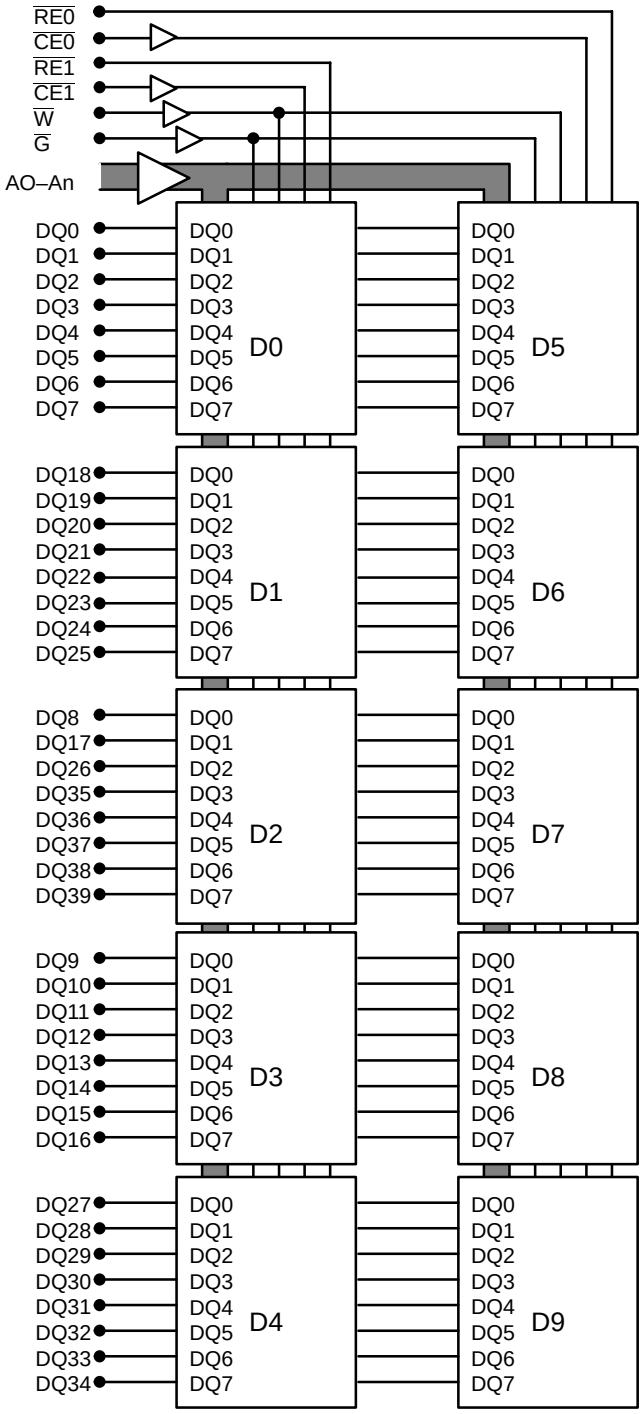
WORD ORGANIZATION	*Base Memory Device D0 to D4	ADDRESS FIELD
512K X 40	4M (X8)	A0 – A9
2M X 40	16M (X8)	A0 – A10
8M X 40	8M (X8)	A0 – A11
32M X 40	32M (X8)	TBD

* NOTE: The BASE MEMORY DEVICE columns give the total device capacity in bits and the data interface word width.

NOTE: There shall be one bypass capacitor between VDD and VSS fore each memory device on the card. The value of the capacitors will be determined by the memory devices used.

FIGURE 4.4.3–2 E
88 PIN, BY 40 DRAM CARD 1 BANK USING BY 8 DEVICES

BLOCK DIAGRAM for 1M/4M/16M/64M X 40 USING X8 DRAM



WORD ORGANIZATION	*Base Memory Device D0 to D9	ADDRESS FIELD
1M X 40	4M (X8)	A0 – A9
4M X 40	16M (X8)	A0 – A10
16M X 40	64M (X8)	A0 – A11
64M X 40	256M (X8)	TBD

* NOTE: The BASE MEMORY DEVICE columns give the total device capacity in bits and the data interface word width.

NOTE: There shall be one bypass capacitor between VDD and VSS fore each pair of memory devices on the card. The value of the capacitors will be determined by the memory devices used.

FIGURE 4.4.3–2 F
88 PIN, BY 40 DRAM CARD 2 BANK USING BY 8 DEVICES